What is claimed is:

1. A semiconductor device, comprising:

a semiconductor chip,

a chip-mounting substrate which is provided with said semiconductor chip mounted on a top surface thereof and first conductive pads formed on a bottom surface thereof and connected with said semiconductor chip electrically,

solder balls formed on said first conductive pads,

a printed circuit board on which second conductive pads connected with said solder balls are formed, and

underfill material injected into a clearance formed between said chip-mounting substrate and said printed circuit board,

wherein unevenness is formed on a surface which is brought into contact with said underfill material of at least one of said chip-mounting substrate and said printed circuit board.

2. A semiconductor device according to claim 1, wherein:

said unevenness is formed on said first conductive pads or on said second conductive pads selectively.

3. A semiconductor device according to claim 1, wherein:

said unevenness is shaped into a slit-like configuration or into a dimple-like configuration.

4. A semiconductor device, comprising:

a semiconductor chip,

a lead frame which is provided with said semiconductor chip mounted thereon and electrically connected with said semiconductor chip, and

a printed circuit board including third conductive pads which are formed thereon and brought into contact with said lead frame,

wherein at least one of said lead frame and said printed circuit board is provided with unevennesses at contact surfaces therebetween.

5. A method for fabricating a semiconductor device, comprising the steps of:

forming fourth conductive pads on a bottom surface of a chip-mounting substrate,

forming unevenness on said bottom surface of said chip-mounting substrate,

mounting a semiconductor chip on a top surface of said chip-mounting substrate,

connecting said semiconductor chip with said fourth conductive pads electrically,

forming solder balls on said fourth conductive pads,

assembling said chip-mounting substrate into a printed circuit board by connecting solder balls with fifth conductive pads formed on said printed circuit board, and

injecting underfill material into a clearance formed between said chip-mounting substrate and said printed circuit board.

6. A method for fabricating a semiconductor device according to claim 5, wherein:

said step of forming said unevenness on said bottom surface of said chip-mounting substrate comprises the step of forming unevennesses on said fourth conductive pads selectively.

7. A method for fabricating a semiconductor device, comprising the steps of:

forming sixth conductive pads on a bottom surface of a chip-mounting substrate,

mounting a semiconductor chip on a top surface of said chip-mounting substrate,

connecting said semiconductor chip with said sixth conductive pads electrically,

forming solder balls on said sixth conductive pads,

forming unevenness on a surface of a printed circuit board on which seventh conductive pads are formed,

assembling said chip-mounting substrate into said printed circuit board by connecting said solder balls with said seventh conductive pads formed on said printed circuit board, and

injected underfill material into a clearance formed between said chip-mounting substrate and said printed circuit board.

8. A method for fabricating a semiconductor device according to claim 7, wherein:

said step of forming said unevenness on said surface of said printed circuit board comprises the step of forming unevennesses on said seventh conductive pads selectively.

9. A method for fabricating a semiconductor device, comprising the steps of:

forming eighth conductive pads on a bottom surface of a chip-mounting substrate,

forming a first unevenness on a bottom surface of said chip-mounting substrate,

mounting a semiconductor chip on a top surface of said chip-mounting substrate,

connecting said semiconductor chip with said eighth conductive pads electrically,

forming solder balls on said eighth conductive pads,

forming a second unevenness on a surface of a printed circuit board on which ninth conductive pads are formed,

assembling said chip-mounting substrate into said printed circuit board by connecting said solder balls with said ninth conductive pads, and

injecting underfill material into a clearance formed between said chip-mooting substrate and said printed circuit board.

10. A method for fabricating a semiconductor device according to claim 9, wherein:

said step of forming said first unevenness comprises the step of forming unevennesses on surfaces of said eighth

conductive pads selectively, and

said step of forming said second unevenness comprises the step of forming unevennesses on surfaces of said ninth conductive pads selectively.

11. A method for fabricating a semiconductor device, comprising the steps of:

forming unevennesses on predetermined parts of a lead frame,

mounting a semiconductor chip on said lead frame,

connecting said semiconductor chip with said lead frame electrically, and

assembling said lead frame on which said semiconductor chip is mounted into a printed circuit board by bringing said unevennesses formed on said lead frame into contact with tenth conductive pads formed on said printed circuit board.

12. A method for fabricating a semiconductor device, comprising the steps of:

mounting a semiconductor chip on a lead frame,

forming unevennesses on surfaces of eleventh conductive pads formed on a printed circuit board, and

assembling said lead frame on which said semiconductor chip is mounted into said printed circuit board by connecting said lead frame with said eleventh conductive pads on which said unevennesses are formed.

13. A method for fabricating a semiconductor device,

comprising the steps of:

forming first unevennesses on predetermined parts of a lead frame,

mounting a semiconductor chip on said lead frame,

connecting said semiconductor chip with said lead frame electrically,

forming second unevennesses on surfaces of twelfth conductive pads formed on a printed circuit board, and

assembling said lead frame on which said semiconductor chip is mounted into said printed circuit board by bringing said first unevennesses formed on said lead frame into contact with said second unevennesses formed on said twelfth conductive pads.